



<b>Title of Change:</b>	Wafer Level Package (WLP) fab site change from Gunma, Japan to Niigata, Japan.			
<b>Proposed first ship date:</b>	21 March 2016			
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Akira.Yoneyama@onsemi.com">Akira.Yoneyama@onsemi.com</a>			
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Makoto.Nakaoka@onsemi.com">Makoto.Nakaoka@onsemi.com</a>			
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <a href="mailto:Satoru.Fujinuma@onsemi.com">Satoru.Fujinuma@onsemi.com</a>			
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.			
<b>Change Part Identification:</b>	Products manufactured at Niigata will be printed Date Code from 1547 on shipping MPN label.			
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____			
<b>Change Sub-Category(s):</b>	<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____			
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Gunma, Japan ON Niigata, Japan <input type="checkbox"/> External Foundry/Subcon site(s)			
<b>Description and Purpose:</b>				
This is a Final Notification to announce the continuous supply of products and increase supply capacity to support increased demand. The Wafer level package location will move from Gunma, Japan to Niigata, Japan. Most of the equipment and personnel were transferred from Gunma to the Niigata site. The Niigata site is ISO/TS16949 certified.				
<b>Reliability Data Summary:</b>				
<b>PACKAGE :WLCSP179</b>				
<b>Test</b>	<b>Specification</b>	<b>Condition</b>	<b>Interval</b>	<b>Results</b>
HTOL	JESD22-A108	Tj=125°C, Vcc=operating max	1008 hrs	0/77
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/77
THB	JESD22-A101	85°C, 85% RH, V= operating max	1008 hrs	0/77
<b>PACKAGE :WLCSP36</b>				
<b>Test</b>	<b>Specification</b>	<b>Condition</b>	<b>Interval</b>	<b>Results</b>
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/77
<b>Electrical Characteristic Summary:</b>				
There is no change in the electrical performance. Datasheet specifications remain unchanged.				
<b>List of Affected Standard Parts:</b>				
LE2464CXATBG				